What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details

Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	60MHz
Connectivity	I²C, IrDA, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	44
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at32uc3b0128-z2ur

- **On-Chip Debug System (JTAG interface)**
  - **Nexus Class 2+, Runtime Control, Non-Intrusive Data and Program Trace**
- **64-pin TQFP/QFN (44 GPIO pins), 48-pin TQFP/QFN (28 GPIO pins)**
- **5V Input Tolerant I/Os, including 4 high-drive pins**
- **Single 3.3V Power Supply or Dual 1.8V-3.3V Power Supply**

1. Description

The AT32UC3B is a complete System-On-Chip microcontroller based on the AVR32 UC RISC processor running at frequencies up to 60 MHz. AVR32 UC is a high-performance 32-bit RISC microprocessor core, designed for cost-sensitive embedded applications, with particular emphasis on low power consumption, high code density and high performance.

The processor implements a Memory Protection Unit (MPU) and a fast and flexible interrupt controller for supporting modern operating systems and real-time operating systems.

Higher computation capability is achieved using a rich set of DSP instructions.

The AT32UC3B incorporates on-chip Flash and SRAM memories for secure and fast access.

The Peripheral Direct Memory Access controller enables data transfers between peripherals and memories without processor involvement. PDCA drastically reduces processing overhead when transferring continuous and large data streams between modules within the MCU.

The Power Manager improves design flexibility and security: the on-chip Brown-Out Detector monitors the power supply, the CPU runs from the on-chip RC oscillator or from one of external oscillator sources, a Real-Time Clock and its associated timer keeps track of the time.

The Timer/Counter includes three identical 16-bit timer/counter channels. Each channel can be independently programmed to perform frequency measurement, event counting, interval measurement, pulse generation, delay timing and pulse width modulation.

The PWM modules provides seven independent channels with many configuration options including polarity, edge alignment and waveform non overlap control. One PWM channel can trigger ADC conversions for more accurate close loop control implementations.

The AT32UC3B also features many communication interfaces for communication intensive applications. In addition to standard serial interfaces like USART, SPI or TWI, other interfaces like flexible Synchronous Serial Controller and USB are available. The USART supports different communication modes, like SPI mode.

The Synchronous Serial Controller provides easy access to serial communication protocols and audio standards like I^{2}S, UART or SPI.

The Full-Speed USB 2.0 Device interface supports several USB Classes at the same time thanks to the rich End-Point configuration. The Embedded Host interface allows device like a USB Flash disk or a USB printer to be directly connected to the processor.

Atmel offers the QTouch library for embedding capacitive touch buttons, sliders, and wheels functionality into AVR microcontrollers. The patented charge-transfer signal acquisition offers robust sensing and included fully debounced reporting of touch keys and includes Adjacent Key Suppression® (AKS®) technology for unambiguous detection of key events. The easy-to-use QTouch Suite toolchain allows you to explore, develop, and debug your own touch applications.

AT32UC3B integrates a class 2+ Nexus 2.0 On-Chip Debug (OCD) System, with non-intrusive real-time trace, full-speed read/write memory access in addition to basic runtime control. The Nanotrace interface enables trace feature for JTAG-based debuggers.

Table 5-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
Serial Peripheral Interface - SPI0				
MISO	Master In Slave Out	I/O		
MOSI	Master Out Slave In	I/O		
NPCS0 - NPCS3	SPI Peripheral Chip Select	I/O	Low	
SCK	Clock	Output		
Synchronous Serial Controller - SSC				
RX_CLOCK	SSC Receive Clock	I/O		
RX_DATA	SSC Receive Data	Input		
RX_FRAME_SYNC	SSC Receive Frame Sync	I/O		
TX_CLOCK	SSC Transmit Clock	I/O		
TX_DATA	SSC Transmit Data	Output		
TX_FRAME_SYNC	SSC Transmit Frame Sync	I/O		
Timer/Counter - TIMER				
A0	Channel 0 Line A	I/O		
A1	Channel 1 Line A	I/O		
A2	Channel 2 Line A	I/O		
B0	Channel 0 Line B	I/O		
B1	Channel 1 Line B	I/O		
B2	Channel 2 Line B	I/O		
CLK0	Channel 0 External Clock Input	Input		
CLK1	Channel 1 External Clock Input	Input		
CLK2	Channel 2 External Clock Input	Input		
Two-wire Interface - TWI				
SCL	Serial Clock	I/O		
SDA	Serial Data	I/O		
Universal Synchronous Asynchronous Receiver Transmitter - USART0, USART1, USART2				
CLK	Clock	I/O		
CTS	Clear To Send	Input		

The register file is organized as sixteen 32-bit registers and includes the Program Counter, the Link Register, and the Stack Pointer. In addition, register R12 is designed to hold return values from function calls and is used implicitly by some instructions.

6.3   The AVR32UC CPU

The AVR32UC CPU targets low- and medium-performance applications, and provides an advanced OCD system, no caches, and a Memory Protection Unit (MPU). Java acceleration hardware is not implemented.

AVR32UC provides three memory interfaces, one High Speed Bus master for instruction fetch, one High Speed Bus master for data access, and one High Speed Bus slave interface allowing other bus masters to access data RAMs internal to the CPU. Keeping data RAMs internal to the CPU allows fast access to the RAMs, reduces latency, and guarantees deterministic timing. Also, power consumption is reduced by not needing a full High Speed Bus access for memory accesses. A dedicated data RAM interface is provided for communicating with the internal data RAMs.

A local bus interface is provided for connecting the CPU to device-specific high-speed systems, such as floating-point units and fast GPIO ports. This local bus has to be enabled by writing the LOCEN bit in the CPUCR system register. The local bus is able to transfer data between the CPU and the local bus slave in a single clock cycle. The local bus has a dedicated memory range allocated to it, and data transfers are performed using regular load and store instructions. Details on which devices that are mapped into the local bus space is given in the Memories chapter of this data sheet.

displays the contents of AVR32UC.

6.6   Module Configuration

All AT32UC3B parts do not implement the same CPU and Architecture Revision.

Table 6-5.   CPU and Architecture Revision

Part Name	Architecture Revision
AT32UC3Bx512	2
AT32UC3Bx256	1
AT32UC3Bx128	1
AT32UC3Bx64	1

8. Boot Sequence

This chapter summarizes the boot sequence of the AT32UC3B. The behaviour after power-up is controlled by the Power Manager. For specific details, refer to section Power Manager (PM).

8.1 Starting of clocks

After power-up, the device will be held in a reset state by the Power-On Reset circuitry, until the power has stabilized throughout the device. Once the power has stabilized, the device will use the internal RC Oscillator as clock source.

On system start-up, the PLLs are disabled. All clocks to all modules are running. No clocks have a divided frequency, all parts of the system recieves a clock with the same frequency as the internal RC Oscillator.

8.2 Fetching of initial instructions

After reset has been released, the AVR32 UC CPU starts fetching instructions from the reset address, which is 0x8000_0000. This address points to the first address in the internal Flash.

The code read from the internal Flash is free to configure the system to use for example the PLLs, to divide the frequency of the clock routed to some of the peripherals, and to gate the clocks to unused peripherals.

When powering up the device, there may be a delay before the voltage has stabilized, depending on the rise time of the supply used. The CPU can start executing code as soon as the supply

is above the POR threshold, and before the supply is stable. Before switching to a high-speed clock source, the user should use the BOD to make sure the VDDCORE is above the minimum level.

9.3 Regulator Characteristics

Table 9-2. Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{VDDIN}	Supply voltage (input)		3	3.3	3.6	V
V_{VDDOUT}	Supply voltage (output)		1.70	1.8	1.85	V
I_{OUT}	Maximum DC output current	V_{VDDIN} = 3.3V			100	mA
I_{SCR}	Static Current of internal regulator	Low Power mode (stop, deep stop or static) at T_A = 25°C		10		µA

Table 9-3. Decoupling Requirements

Symbol	Parameter	Conditions	Typ.	Technology	Unit
C_{IN1}	Input Regulator Capacitor 1		1	NPO	nF
C_{IN2}	Input Regulator Capacitor 2		4.7	X7R	µF
C_{OUT1}	Output Regulator Capacitor 1		470	NPO	pF
C_{OUT2}	Output Regulator Capacitor 2		2.2	X7R	µF

9.4 Analog Characteristics

9.4.1 ADC Reference

Table 9-4. Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{ADVREF}	Analog voltage reference (input)		2.6		3.6	V

Table 9-5. Decoupling Requirements

Symbol	Parameter	Conditions	Typ.	Technology	Unit
C_{VREF1}	Voltage reference Capacitor 1		10	NPO	nF
C_{VREF2}	Voltage reference Capacitor 2		1	NPO	uF

9.4.2 BOD

Table 9-6. BOD Level Values

Symbol	Parameter Value	Conditions	Min.	Typ.	Max.	Unit
BODLEVEL	00 0000b			1.44		V
	01 0111b			1.52		V
	01 1111b			1.61		V
	10 0111b			1.71		V

Table 9-6 describes the values of the BODLEVEL field in the flash FGPFR register.

Table 9-7. BOD Timing

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
T_{BOD}	Minimum time with VDDCORE < VBOD to detect power failure	Falling VDDCORE from 1.8V to 1.1V		300	800	ns

9.4.3 Reset Sequence

Table 9-8. Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{DDRR}	VDDCORE rise rate to ensure power-on-reset		2.5			V/ms
V_{DDFR}	VDDCORE fall rate to ensure power-on-reset		0.01		400	V/ms
V_{POR+}	Rising threshold voltage: voltage up to which device is kept under reset by POR on rising VDDCORE	Rising VDDCORE: $V_{RESTART}$ -> V_{POR+}	1.4	1.55	1.65	V
V_{POR-}	Falling threshold voltage: voltage when POR resets device on falling VDDCORE	Falling VDDCORE: 1.8V -> V_{POR+}	1.2	1.3	1.4	V
$V_{RESTART}$	On falling VDDCORE, voltage must go down to this value before supply can rise again to ensure reset signal is released at V_{POR+}	Falling VDDCORE: 1.8V -> $V_{RESTART}$	-0.1		0.5	V
T_{POR}	Minimum time with VDDCORE < V_{POR-}	Falling VDDCORE: 1.8V -> 1.1V		15		µs
T_{RST}	Time for reset signal to be propagated to system			200	400	µs
T_{SSU1}	Time for Cold System Startup: Time for CPU to fetch its first instruction (RCosc not calibrated)		480		960	µs
T_{SSU2}	Time for Hot System Startup: Time for CPU to fetch its first instruction (RCosc calibrated)			420		µs

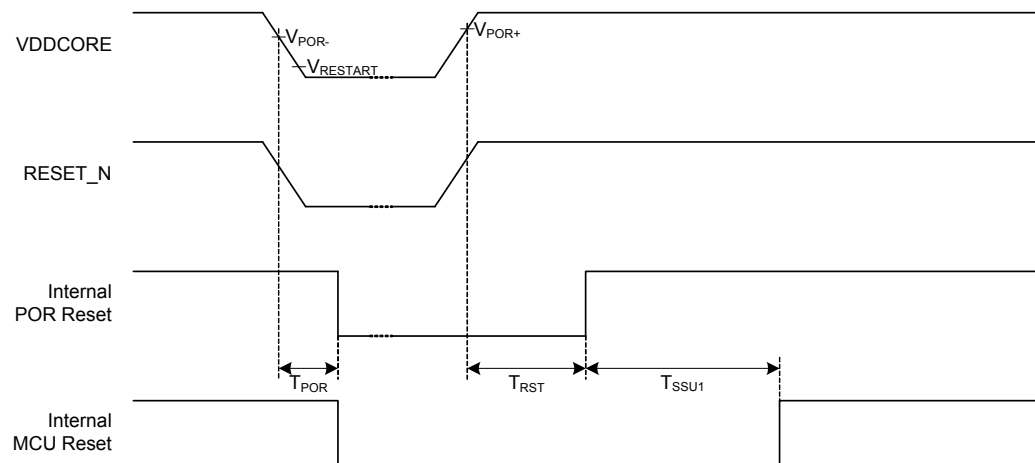**Figure 9-1.** MCU Cold Start-Up RESET_N tied to VDDIN

VDDCORE

V_{POR-}
$V_{RESTART}$
V_{POR+}

RESET_N

Internal
POR Reset

T_{POR} T_{RST} T_{SSU1}

Internal
MCU Reset

Figure 9-2. MCU Cold Start-Up RESET_N Externally Driven

VDDCORE

V_{POR-}
$V_{RESTART}$
V_{POR+}

RESET_N

Internal
POR Reset

T_{POR} T_{RST} T_{SSU1}
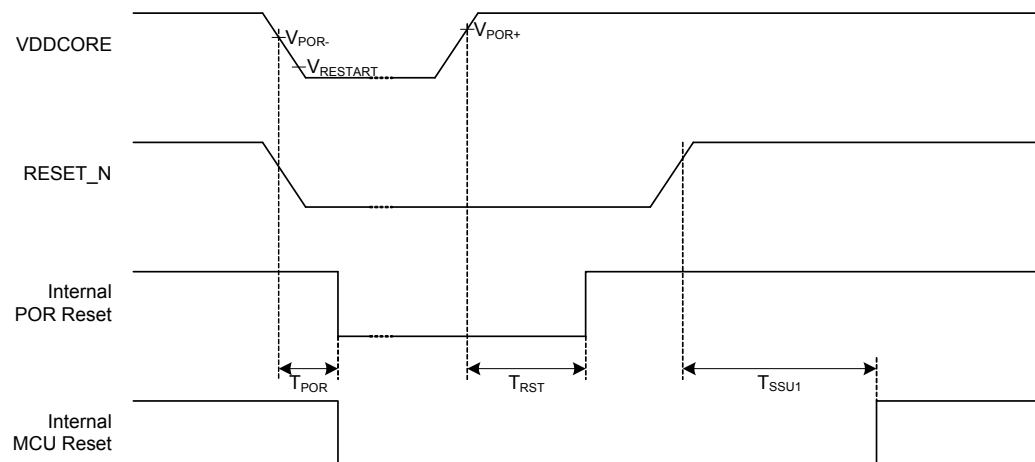
Internal
MCU Reset

Figure 9-3. MCU Hot Start-Up

VDDCORE

RESET_N
BOD Reset
WDT Reset

T_{SSU2}

Internal
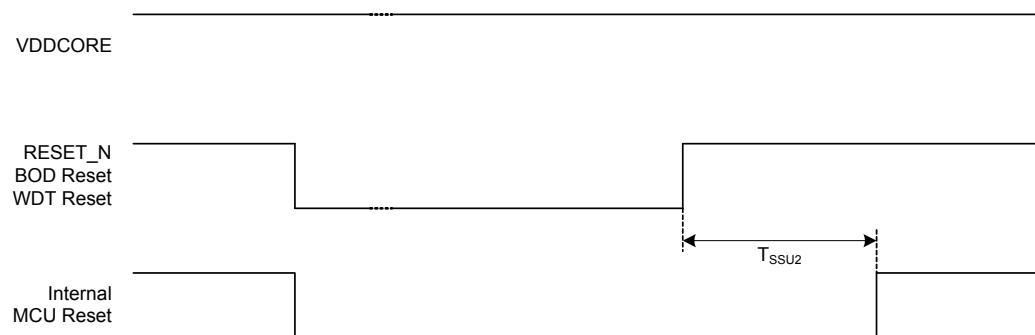MCU Reset

In dual supply configuration, the power up sequence must be carefully managed to ensure a safe startup of the device in all conditions.

The power up sequence must ensure that the internal logic is safely powered when the internal reset (Power On Reset) is released and that the internal Flash logic is safely powered when the CPU fetch the first instructions.

9.5 Power Consumption

The values in Table 9-10, Table 9-11 on page 43 and Table 9-12 on page 44 are measured values of power consumption with operating conditions as follows:

- $V_{DDIO} = V_{DDANA} = 3.3V$
- $V_{DDCORE} = V_{DDPLL} = 1.8V$
- $T_A = 25°C$, $T_A = 85°C$
- I/Os are configured in input, pull-up enabled.

Figure 9-5. Measurement Setup
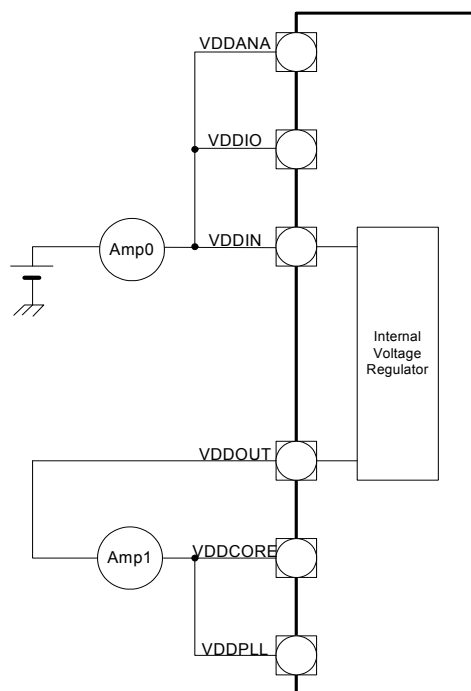
The following tables represent the power consumption measured on the power supplies.

9.6 System Clock Characteristics

These parameters are given in the following conditions:

- V_{DDCORE} = 1.8V
- Ambient Temperature = 25°C

9.6.1 CPU/HSB Clock Characteristics

Table 9-13. Core Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPCPU})$	CPU Clock Frequency				60	MHz
t_{CPCPU}	CPU Clock Period		16.6			ns

9.6.2 PBA Clock Characteristics

Table 9-14. PBA Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPPBA})$	PBA Clock Frequency				60	MHz
t_{CPPBA}	PBA Clock Period		16.6			ns

9.6.3 PBB Clock Characteristics

Table 9-15. PBB Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPPBB})$	PBB Clock Frequency				60	MHz
t_{CPPBB}	PBB Clock Period		16.6			ns

9.7.3 Main Oscillators

Table 9-18. Main Oscillators Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPMAIN})$	Oscillator Frequency	External clock on XIN			50	MHz
		Crystal	0.4		20	MHz
C_{L1}, C_{L2}	Internal Load Capacitance ($C_{L1} = C_{L2}$)			7		pF
ESR	Crystal Equivalent Series Resistance				75	Ω
	Duty Cycle		40	50	60	%
t_{ST}	Startup Time	f = 400 KHz f = 8 MHz f = 16 MHz f = 20 MHz			25 4 1.4 1	ms
t_{CH}	XIN Clock High Half-period		0.4 t_{CP}		0.6 t_{CP}	
t_{CL}	XIN Clock Low Half-period		0.4 t_{CP}		0.6 t_{CP}	
C_{IN}	XIN Input Capacitance			7		pF
I_{OSC}	Current Consumption	Active mode at 400 KHz. Gain = G0 Active mode at 8 MHz. Gain = G1 Active mode at 16 MHz. Gain = G2 Active mode at 20 MHz. Gain = G3		30 45 95 205		µA

9.7.4 Phase Lock Loop

Table 9-19. Phase Lock Loop Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
F_{OUT}	VCO Output Frequency		80		240	MHz
F_{IN}	Input Frequency		4		16	MHz
I_{PLL}	Current Consumption	Active mode F_{VCO}@96 MHz Active mode F_{VCO}@128 MHz Active mode F_{VCO}@160 MHz		320 410 450		µA
		Standby mode		5		µA

the receive buffer is full. In the interrupt handler code, write a one to the RTSDIS bit in the USART Control Register (CR). This will drive the RTS output high. After the next DMA transfer is started and a receive buffer is available, write a one to the RTSEN bit in the USART CR so that RTS will be driven low.

8. **Corruption after receiving too many bits in SPI slave mode**
   If the USART is in SPI slave mode and receives too much data bits (ex: 9bitsinstead of 8 bits) by the SPI master, an error occurs. After that, the next reception may be corrupted even if the frame is correct and the USART has been disabled, reset by a soft reset and re-enabled.
   Fix/Workaround
   None.

9. **USART slave synchronous mode external clock must be at least 9 times lower in frequency than CLK_USART**
   When the USART is operating in slave synchronous mode with an external clock, the frequency of the signal provided on CLK must be at least 9 times lower than CLK_USART.
   Fix/Workaround
   When the USART is operating in slave synchronous mode with an external clock, provide a signal on CLK that has a frequency at least 9 times lower than CLK_USART.

10. **HMATRIX**

11. **In the PRAS and PRBS registers, the MxPR fields are only two bits**
    In the PRAS and PRBS registers, the MxPR fields are only two bits wide, instead of four bits. The unused bits are undefined when reading the registers.
    Fix/Workaround
    Mask undefined bits when reading PRAS and PRBS.

- *DSP Operations*

1. **Hardware breakpoints may corrupt MAC results**
   Hardware breakpoints on MAC instructions may corrupt the destination register of the MAC instruction.
   Fix/Workaround
   Place breakpoints on earlier or later instructions.

12.2   AT32UC3B0256, AT32UC3B0128, AT32UC3B064, AT32UC3B1256, AT32UC3B1128, AT32UC3B164

All industrial parts labelled with -UES (for engineering samples) are revision B parts.

12.2.1   Rev I, J, K

- *PWM*

1. **PWM channel interrupt enabling triggers an interrupt**
   When enabling a PWM channel that is configured with center aligned period (CALG=1), an interrupt is signalled.
   Fix/Workaround
   When using center aligned mode, enable the channel and read the status before channel interrupt is enabled.

2. **PWN counter restarts at 0x0001**
   The PWM counter restarts at 0x0001 and not 0x0000 as specified. Because of this the first PWM period has one more clock cycle.
   Fix/Workaround
   - The first period is 0x0000, 0x0001, ..., period.
   - Consecutive periods are 0x0001, 0x0002, ..., period.

3. **PWM update period to a 0 value does not work**
   It is impossible to update a period equal to 0 by the using the PWM update register (PWM_CUPD).
   Fix/Workaround
   Do not update the PWM_CUPD register with a value equal to 0.

4. **SPI**

5. **SPI Slave / PDCA transfer: no TX UNDERRUN flag**
   There is no TX UNDERRUN flag available, therefore in SPI slave mode, there is no way to be informed of a character lost in transmission.
   Fix/Workaround
   For PDCA transfer: none.

6. **SPI bad serial clock generation on 2nd chip_select when SCBR=1, CPOL=1, and NCPHA=0**
   When multiple chip selects (CS) are in use, if one of the baudrates equal 1 while one (CSRn.SCBR=1) of the others do not equal 1, and CSRn.CPOL=1 and CSRn.NCPHA=0, then an additional pulse will be generated on SCK.
   Fix/Workaround
   When multiple CS are in use, if one of the baudrates equals 1, the others must also equal 1 if CSRn.CPOL=1 and CSRn.NCPHA=0.

7. **SPI Glitch on RXREADY flag in slave mode when enabling the SPI or during the first transfer**
   In slave mode, the SPI can generate a false RXREADY signal during enabling of the SPI or during the first transfer.
   Fix/Workaround
   1. Set slave mode, set required CPOL/CPHA.
   2. Enable SPI.

- Processor and Architecture

1. **LDM instruction with PC in the register list and without ++ increments Rp**
   For LDM with PC in the register list: the instruction behaves as if the ++ field is always set, ie the pointer is always updated. This happens even if the ++ field is cleared. Specifically, the increment of the pointer is done in parallel with the testing of R12.
   Fix/Workaround
   None.

2. **RETE instruction does not clear SREG[L] from interrupts**
   The RETE instruction clears SREG[L] as expected from exceptions.
   Fix/Workaround
   When using the STCOND instruction, clear SREG[L] in the stacked value of SR before returning from interrupts with RETE.

3. **Privilege violation when using interrupts in application mode with protected system stack**
   If the system stack is protected by the MPU and an interrupt occurs in application mode, an MPU DTLB exception will occur.
   Fix/Workaround
   Make a DTLB Protection (Write) exception handler which permits the interrupt request to be handled in privileged mode.

4. **USART**

5. **ISO7816 info register US_NER cannot be read**
   The NER register always returns zero.
   Fix/Workaround
   None.

6. **ISO7816 Mode T1: RX impossible after any TX**
   RX impossible after any TX.
   Fix/Workaround
   SOFT_RESET on RX+ Config US_MR + Config_US_CR.

7. **The RTS output does not function correctly in hardware handshaking mode**
   The RTS signal is not generated properly when the USART receives data in hardware handshaking mode. When the Peripheral DMA receive buffer becomes full, the RTS output should go high, but it will stay low.
   Fix/Workaround
   Do not use the hardware handshaking mode of the USART. If it is necessary to drive the RTS output high when the Peripheral DMA receive buffer becomes full, use the normal mode of the USART. Configure the Peripheral DMA Controller to signal an interrupt when the receive buffer is full. In the interrupt handler code, write a one to the RTSDIS bit in the USART Control Register (CR). This will drive the RTS output high. After the next DMA transfer is started and a receive buffer is available, write a one to the RTSEN bit in the USART CR so that RTS will be driven low.

8. **Corruption after receiving too many bits in SPI slave mode**
   If the USART is in SPI slave mode and receives too much data bits (ex: 9bitsinstead of 8 bits) by the SPI master, an error occurs. After that, the next reception may be corrupted

2. **Transfer error will stall a transmit peripheral handshake interface**
   If a transfer error is encountered on a channel transmitting to a peripheral, the peripheral handshake of the active channel will stall and the PDCA will not do any more transfers on the affected peripheral handshake interface.
   Fix/Workaround
   Disable and then enable the peripheral after the transfer error.

3. **TWI**

4. **The TWI RXRDY flag in SR register is not reset when a software reset is performed**
   The TWI RXRDY flag in SR register is not reset when a software reset is performed.
   Fix/Workaround
   After a Software Reset, the register TWI RHR must be read.

5. **TWI in master mode will continue to read data**
   TWI in master mode will continue to read data on the line even if the shift register and the RHR register are full. This will generate an overrun error.
   Fix/Workaround
   To prevent this, read the RHR register as soon as a new RX data is ready.

6. **TWI slave behaves improperly if master acknowledges the last transmitted data byte before a STOP condition**
   In I2C slave transmitter mode, if the master acknowledges the last data byte before a STOP condition (what the master is not supposed to do), the following TWI slave receiver mode frame may contain an inappropriate clock stretch. This clock stretch can only be stopped by resetting the TWI.
   Fix/Workaround
   If the TWI is used as a slave transmitter with a master that acknowledges the last data byte before a STOP condition, it is necessary to reset the TWI before entering slave receiver mode.

7. **GPIO**

8. **PA29 (TWI SDA) and PA30 (TWI SCL) GPIO VIH (input high voltage) is 3.6V max instead of 5V tolerant**
   The following GPIOs are not 5V tolerant: PA29 and PA30.
   Fix/Workaround
   None.

- *TC*

1. **Channel chaining skips first pulse for upper channel**
   When chaining two channels using the Block Mode Register, the first pulse of the clock between the channels is skipped.
   Fix/Workaround
   Configure the lower channel with RA = 0x1 and RC = 0x2 to produce a dummy clock cycle for the upper channel. After the dummy cycle has been generated, indicated by the SR.CPCS bit, reconfigure the RA and RC registers for the lower channel with the real values.

7. **ISO7816 Mode T1: RX impossible after any TX**
RX impossible after any TX.
Fix/Workaround
SOFT_RESET on RX+ Config US_MR + Config_US_CR.

8. **The RTS output does not function correctly in hardware handshaking mode**
The RTS signal is not generated properly when the USART receives data in hardware hand-shaking mode. When the Peripheral DMA receive buffer becomes full, the RTS output should go high, but it will stay low.
Fix/Workaround
Do not use the hardware handshaking mode of the USART. If it is necessary to drive the RTS output high when the Peripheral DMA receive buffer becomes full, use the normal mode of the USART. Configure the Peripheral DMA Controller to signal an interrupt when the receive buffer is full. In the interrupt handler code, write a one to the RTSDIS bit in the USART Control Register (CR). This will drive the RTS output high. After the next DMA trans-fer is started and a receive buffer is available, write a one to the RTSEN bit in the USART CR so that RTS will be driven low.

9. **Corruption after receiving too many bits in SPI slave mode**
If the USART is in SPI slave mode and receives too much data bits (ex: 9bitsinstead of 8 bits) by the SPI master, an error occurs. After that, the next reception may be corrupted even if the frame is correct and the USART has been disabled, reset by a soft reset and re-enabled.
Fix/Workaround
None.

10. **USART slave synchronous mode external clock must be at least 9 times lower in fre-quency than CLK_USART**
When the USART is operating in slave synchronous mode with an external clock, the fre-quency of the signal provided on CLK must be at least 9 times lower than CLK_USART.
Fix/Workaround
When the USART is operating in slave synchronous mode with an external clock, provide a signal on CLK that has a frequency at least 9 times lower than CLK_USART.

11. **HMATRIX**

12. **In the PRAS and PRBS registers, the MxPR fields are only two bits**
In the PRAS and PRBS registers, the MxPR fields are only two bits wide, instead of four bits. The unused bits are undefined when reading the registers.
Fix/Workaround
Mask undefined bits when reading PRAS and PRBS.

- *FLASHC*

1. **Reading from on-chip flash may fail after a flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands).**
After a flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands), the following flash read access may return corrupted data. This erratum does not affect write operations to regular flash memory.
Fix/Workaround
The flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands) must be issued from internal RAM. After the write operation, perform a dummy flash page write operation (FLASHC WP). Content and location of this page is not important

Figure 12-1. Timer/Counter clock connections on RevB

Source	Name	Connection
Internal	TIMER_CLOCK1	32KHz Oscillator
	TIMER_CLOCK2	PBA Clock / 4
	TIMER_CLOCK3	PBA Clock / 8
	TIMER_CLOCK4	PBA Clock / 16
	TIMER_CLOCK5	PBA Clock / 32
External	XC0	
	XC1	
	XC2	

7. Spurious interrupt may corrupt core SR mode to exception
If the rules listed in the chapter `Masking interrupt requests in peripheral modules' of the AVR32UC Technical Reference Manual are not followed, a spurious interrupt may occur. An interrupt context will be pushed onto the stack while the core SR mode will indicate an exception. A RETE instruction would then corrupt the stack.
Fix/Workaround
Follow the rules of the AVR32UC Technical Reference Manual. To increase software robustness, if an exception mode is detected at the beginning of an interrupt handler, change the stack interrupt context to an exception context and issue a RETE instruction.

8. CPU cannot operate on a divided slow clock (internal RC oscillator)
CPU cannot operate on a divided slow clock (internal RC oscillator).
Fix/Workaround
Do not run the CPU on a divided slow clock.

9. LDM instruction with PC in the register list and without ++ increments Rp
For LDM with PC in the register list: the instruction behaves as if the ++ field is always set, i.e. the pointer is always updated. This happens even if the ++ field is cleared. Specifically, the increment of the pointer is done in parallel with the testing of R12.
Fix/Workaround
None.

10. RETE instruction does not clear SREG[L] from interrupts
The RETE instruction clears SREG[L] as expected from exceptions.
Fix/Workaround
When using the STCOND instruction, clear SREG[L] in the stacked value of SR before returning from interrupts with RETE.

11. Exceptions when system stack is protected by MPU
RETS behaves incorrectly when MPU is enabled and MPU is configured so that system stack is not readable in unprivileged mode.
Fix/Workaround
Workaround 1: Make system stack readable in unprivileged mode,
or
Workaround 2: Return from supervisor mode using rete instead of rets. This requires: 1. Changing the mode bits from 001b to 110b before issuing the instruction.
Updating the mode bits to the desired value must be done using a single mtsr instruction so

it is done atomically. Even if this step is described in general as not safe in the UC technical reference guide, it is safe in this very specific case.
2. Execute the RETE instruction.

13. Datasheet Revision History

Please note that the referring page numbers in this section are referred to this document. The referring revision in this section are referring to the document revision.

13.1 Rev. L– 01/2012

1.   Updated Mechanical Characteristics section.

13.2 Rev. K– 02/2011

1.   Updated USB section.

2.   Updated Configuration Summary section.

3.   Updated Electrical Characteristics section.

4.   Updated Errata section.

13.3 Rev. J– 12/2010

1.   Updated USB section.

2.   Updated USART section.

3.   Updated TWI section.

4.   Updated PWM section.

5.   Updated Electrical Characteristics section.

13.4 Rev. I – 06/2010

1.   Updated SPI section.

2   Updated Electrical Characteristics section.

13.5 Rev. H – 10/2009

1.   Update datasheet architecture.

2   Add AT32UC3B0512 and AT32UC3B1512 devices description.